'-'' ./01.2'3.4532''

A	2022.4.21	ALL	AOS-AOD950A70		
B	2022.5.26	2,3,4,5	YC-RMX65R1K0SN_ReV1.2		

''-'' .1430<=05:1'

TO-252 N 650V

N-CHANNEL 650V Super-Junction Power MOSFET in a TO-252 Plastic Package.

''-''>.8=?3.1'

$R_{DS(on)}$ C_{rss}

Low $R_{DS(on)}$,low gate charge, low C_{rss}, fast switching, HF Product.

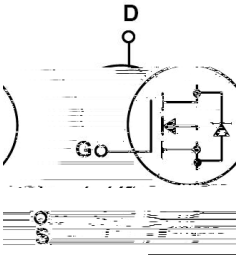
'

''-'' (<<@048=05:1''

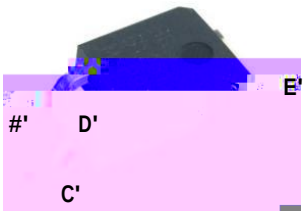
DC/DC

Suited for low voltage applications such as automotive, DC/DC Converters, and high efficiency switching for power management in portable and battery operated products.

''-'' ,A?0/8@.:='&034?0='



''-''B0::0:;'



PIN1 G PIN 2 D PIN 3 S PIN 4 D

''-''7 8390:;'

See Marking Instructions.

'

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	650	V
Drain Current	I_D(Tc=25℃)	5	A
Drain Current - Pulsed	I_{DM}	20	A
Gate-Source Voltage	V_{GS}	±30	V
Single Pulsed Avalanche Energy	E_{AS}	27	mJ
Avalanche Current	I_{AS}	2.5	A
Power Dissipation	P_D(Tc=25℃)	56.5	W
Operating and Storage Temperature Range	T_J,T_{STG}	-55 to 150	℃
Junction-to-Case	$R_{\theta JC}$	2.2	℃/W
Junction-to-Ambient	$R_{\theta JA}$	55	℃/W

'

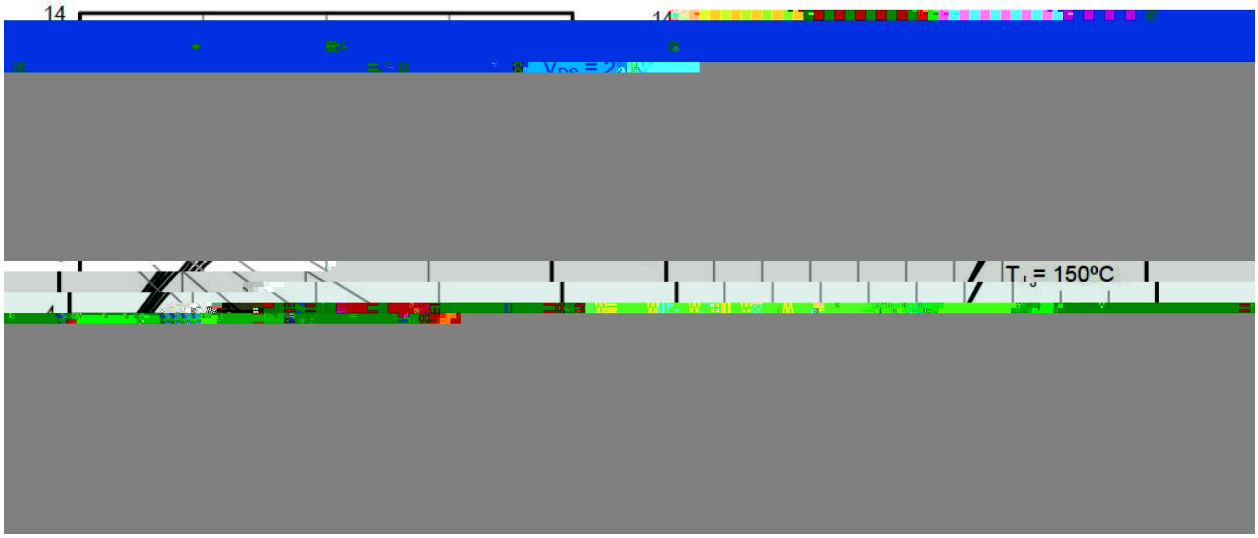
'

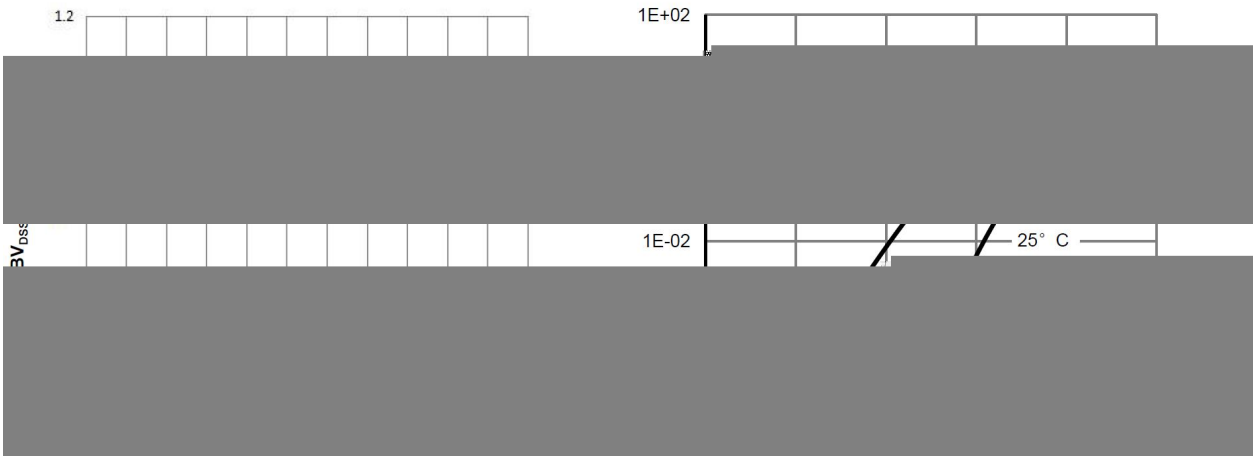
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250μA	650	700		V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=650V V_{GS}=0V T_J=25℃			1.0	μA
Gate-Body Leakage Current, Forward	I_{GSS}	V_{GS}=±30V			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$					

''-'',@.4=3048@'&L8384=.301=041I)8JD" K'

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Continuous Diode Forward Current	I_S				5	A
Total Gate Charge	Q_g	V_{DS}=520V I_D=2A V_{GS}=10V		9.1		nC
Gate-Source Charge	Q_{gs}			2.1		nC
Gate-Drain Charge	Q_{gd}			4.0		nC
Reverse recovery time	T_{rr}	V_R=50 V, I_F=2A, dI_F/dt=100 A/μs		159		ns
Reverse recovery charge	Q_{rr}			0.93		uC

' ' -' ' , @ . 4=3048@'&L8384=.301=04'&?3 / .'





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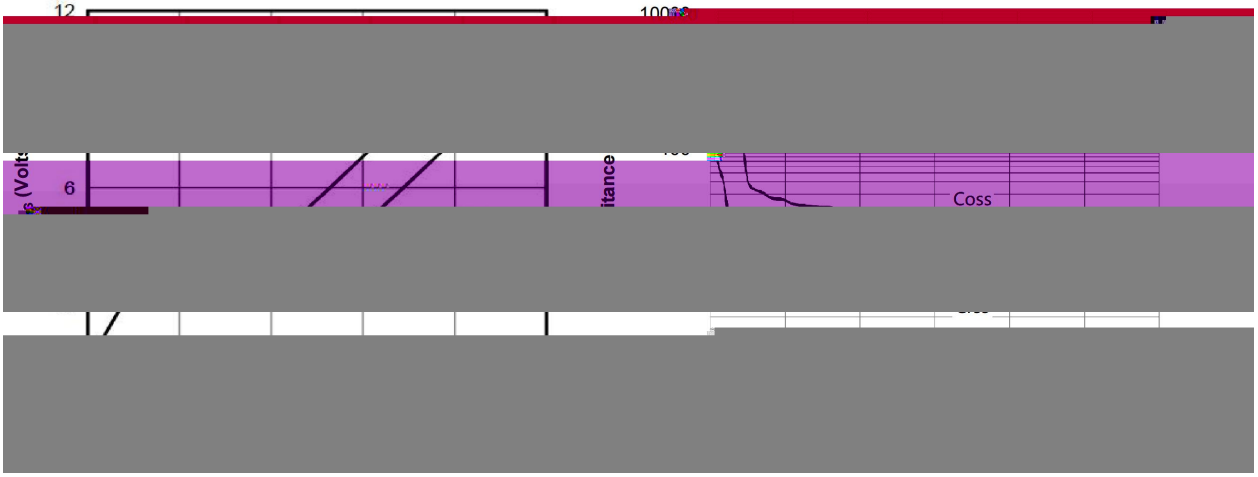
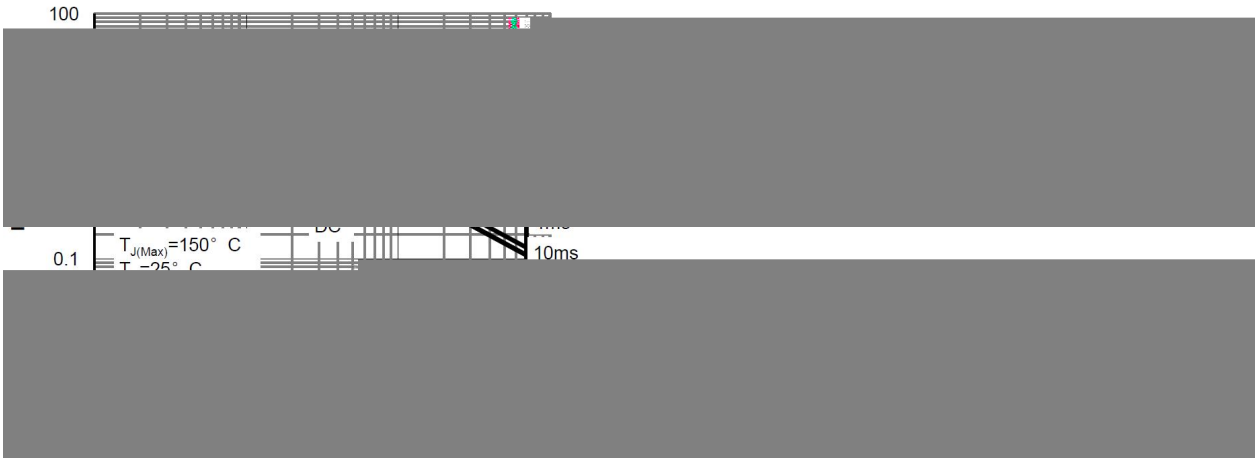
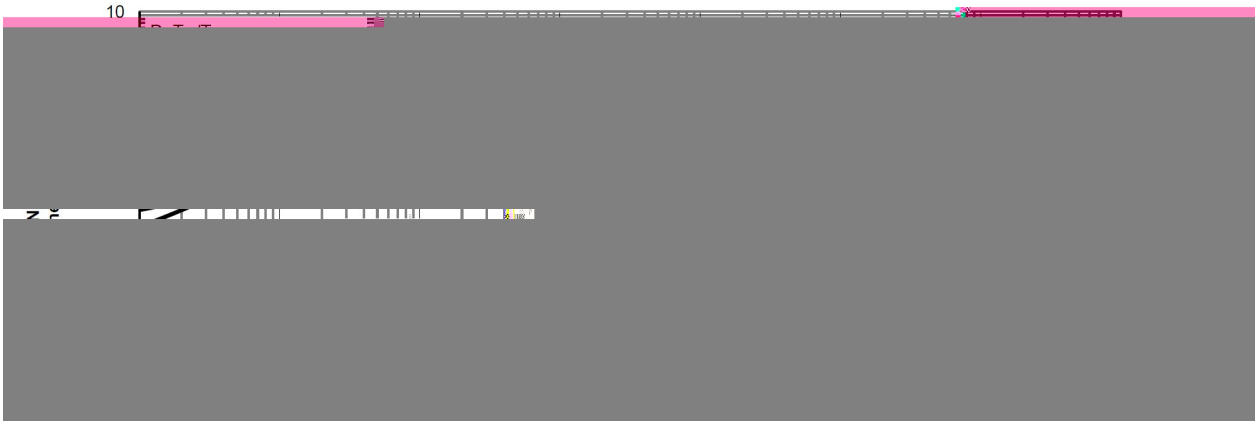
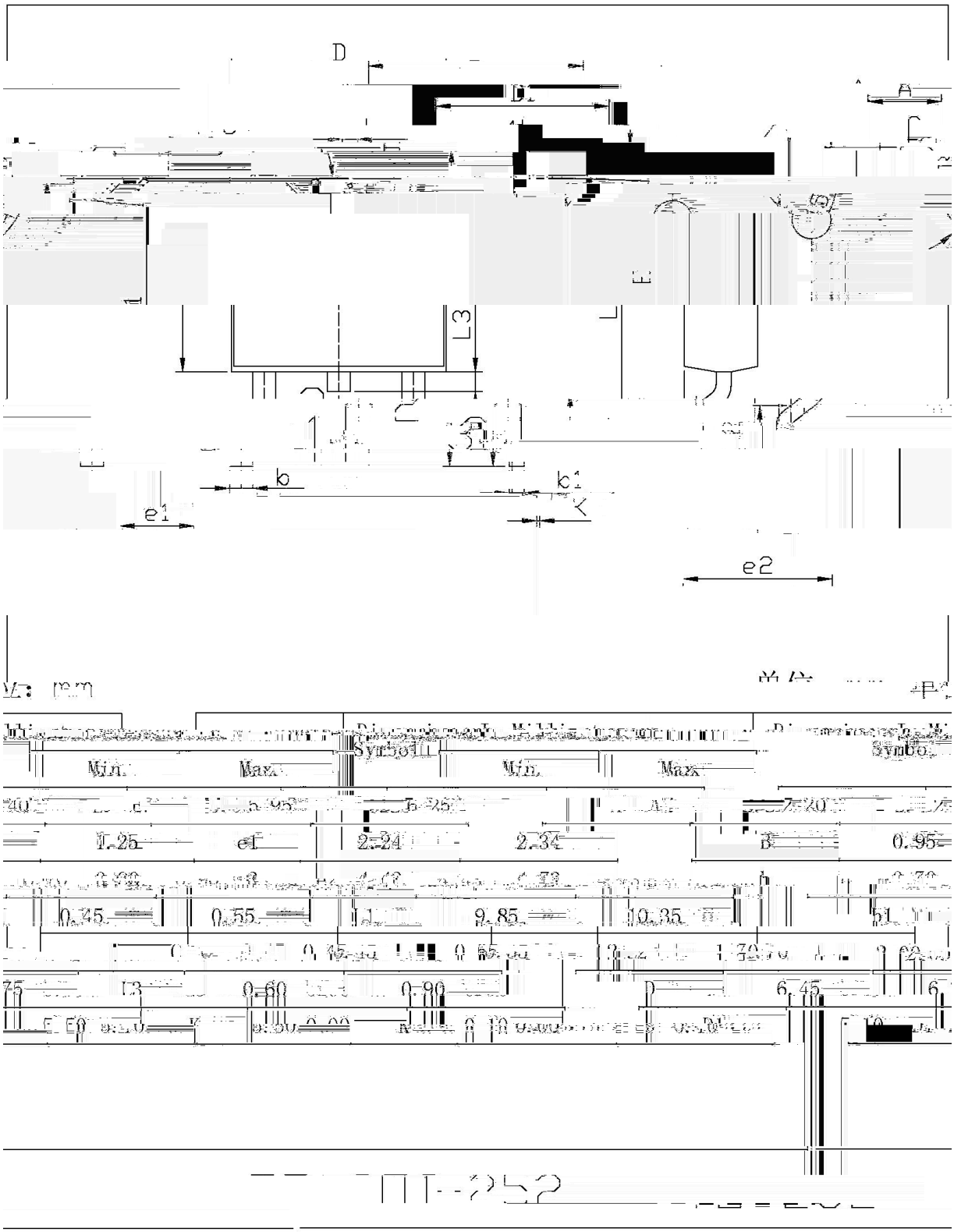


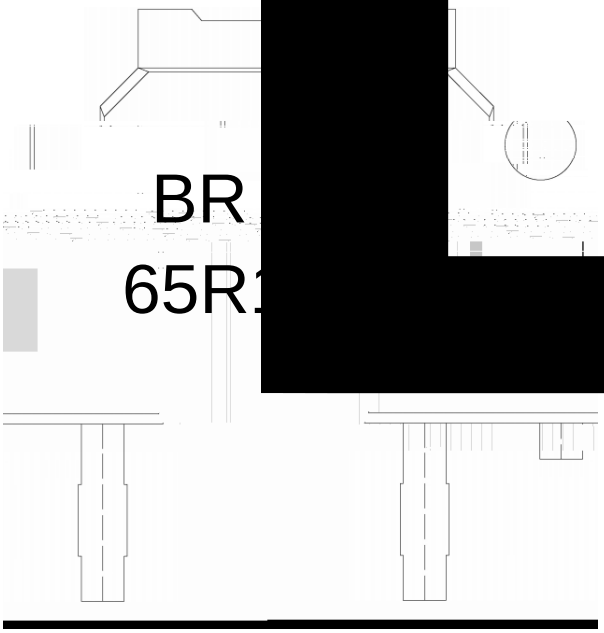




''-''B8498;.' 0H.:105:1'



''-'' 78390:;'N:1=3?4=05:1'



BR

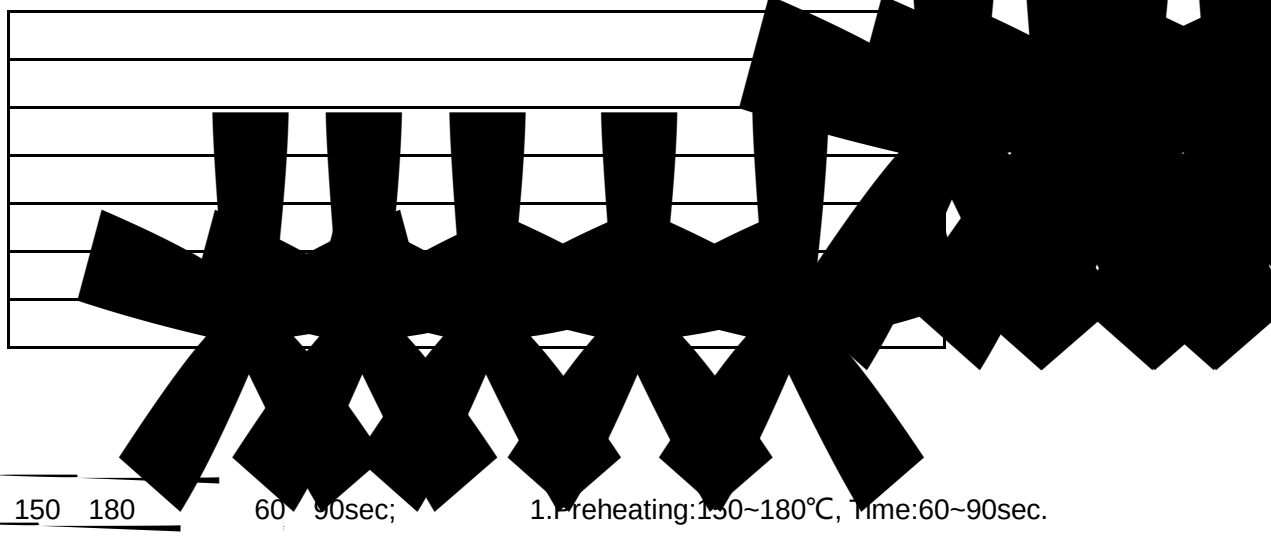
65R1K0C

****

Note:

BR:	Company Code
65R1K0C:	Product Type Code
****:	Lot No. Code, code change with Lot No

I K' ' -' ' Temperature Profile for IR Reflow Soldering(Pb-Fr



1	150 180 60 90sec;	1.Preheating:150~180℃, Time:60~90sec.
2	245±5 5±0.5sec;	2.Peak Temp.:245±5℃, Duration:5±0.5sec.
3	2 10℃/sec.	3. Cooling Speed: 2~10℃/sec.

' ' -' ' ' .101=8:4.'=5'*5@2.30:;'+.8=').1='&5:20=05:1'

260±5℃	10±1 sec.	Temp.:260±5℃	Time:10±1 sec

' ' -' ' B8498;0:;'*B,&0'

/ REEL

Package Type	Units					Dimension (unit mm^3)